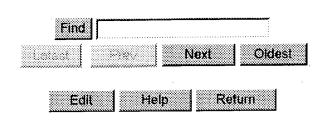
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Searches for User zel-arini (Count = 2877)

Queries 5655 through 5704.



СИТ	[]	t Database	Query	Time Comme
S# U	_		3754896.pn.	2004-
<u>S2877</u>	<u>U</u>	USPI	3734890.pm.	04-08
				12:42:33
S2876	U.	USPT	4002463.pn.	2004-
52070	<u>U</u>		, so .p	Ø4-08
				12:42:26
S2875	U	USPT /	5595345.pn.	2004-
02013	<u></u>			04-08
	_			09:09:20
S2874	U	TDBD DWPI, JPAB, EPAB, USOC, USPT,	PGPB WAFER!	2004-
<u>~~~,</u>	~	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		04-07
				15:22:53
S2873	U	TDBD,DWPI,JPAB,EPAB,USOC,USPT,	PGPB WAFERASSEMBLY	2004-
				04-07
				15:22:01
S2872	$\underline{\mathbf{U}}$	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	pick-up wafer same	2004-
	_/		particles	04-07
				15:09:34
S2871	U	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	pick-up wafer	2004-
			_	04-07
\				15:08:49
S2870	$\underline{\mathbf{U}}$	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal	
		· ·	lines) and wafer and	04-07
			stripping and ((organic	13:25:02
			solvent\$) or alcohol\$)	
			and water and ((inert	
			gas) or nitrogen) and	
			immersing and	
			removing and	
G0050		DODD LIGHT EDAD IDAD DUMIN TODO	maintaining	2004
S2869	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and	04-07
		•	stripping and ((organic	
			suppling and ((organic solvent\$) or alcohol\$)	, 1J, 47, TJ
			and water and ((inert	
			and water and ((mert	

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_				
			gas) or nitrogen) and immersing and removing	2004
<u>\$2868</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert	04-07 c 13:24:32
			gas) or nitrogen) and immersing	
<u>\$2867</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert gas) or nitrogen)	04-07
<u>S2866</u>	U	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water	04-07
<u>S2865</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$)	04-07
<u>S2864</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping	2004- 04-07 13:21:56
<u>S2863</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer	2004- 04-07 13:21:34
<u>S2862</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$ and flotation	2004- 04-07 09:37:44
S2861	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$ and floatation	2004- 04-07 09:37:24
<u>S2860</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$	2004- 04-07 09:35:40
<u>S2859</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD		2004-